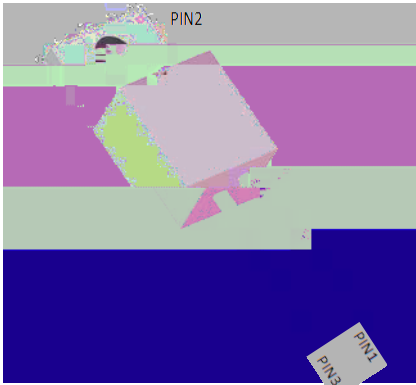


Ultra-Fast Recovery Diodes 8A FRED



Features

- Adopt FRED chip
 - Low forward Voltage drop
 - Fast reverse recovery time
 - High frequency operation
 - High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
 - Guard ring for enhanced ruggedness and long life
- 002 and JESD22-B102
- **Polarity:** As marked

■Maximum Ratings (Tj=25 Unless otherwise specified

PARAMETER	SYMBOL	UNIT	MUR860L
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Device marking code

MUR860L

c(FIG.1)

IO

Surge(Non-repetitive)Forward Current @60Hz half sine-wave, 1 cycle, Tj=25	IFSM	A	50
Current Squared Time @1ms≤t≤8.3ms Tj=25	I²t	A²s	12.5
Storage Temperature	Tstg		-55 ~ +175
Junction Temperature	Tj		-55 ~ +175
Typical Junction capacitance @4V,1MHz	Cj	pF	42



MUR860L

■Electrical Characteristics

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	Min	Typ	Max
Instantaneous forward voltage drop per diode	V_{FM}	V	IFM=8.0A @Tj=25	-	2.15	3.0
			IFM=8.0A @Tj=150	-	-	2.0
DC reverse current at rated DC blocking voltage per diode	I_{RRM1}	uA	VRM=VRRM Tj=25	-	-	5.0
	I_{RRM2}		VRM=VRRM Tj=150	-	25	200
Reverse Recovery Time	Trr	ns	IF=0.5A IRM=1A IRR=0.25A Tj=25	-	17	25
			Tj=25	-	40	-
			Tj=125	-	95	-
Peak recovery current	I_{RRM}	A	Tj=25	-	1.9	-
			Tj=125	-	3.8	-
Reverse recovery charge	Qrr	nC	Tj=25	-	40	-
			Tj=125	-	185	-

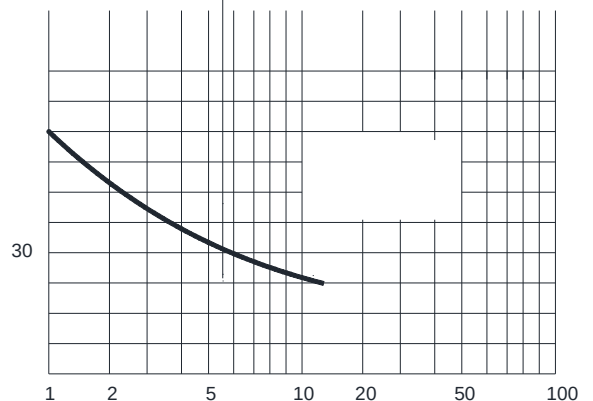
■Thermal Characteristics Tj=25 Unless otherwise specified

PARAMETER		SYMBOL	UNIT	MUR860L
Thermal Resistance	Between junction and case	RθJ-C	/W	2.0
Thermal Resistance	Between junction and Air	RθJ-A	/W	50

■Ordering Information (Example)

PREFERRED P/N	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
MUR860L	Approximate 1.8	50	1000	5000	Tube

■Characteristics (Typical)





Disclaimer

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The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controller